



Materials Declaration Form


IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	19-10-2017
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Representative Title	MDG MD CHAMPION
Authorized Representative *	MDG MD CHAMPION	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
	<p>While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.</p>
Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8L151C2T6	S25B*758XXXZ	A	998Z	19-10-2017
	Amount	UoM	Unit type	ST ECOPACK Grade
	195.10	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7X1.4	48	L Bend	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH- 7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	S25B*758XXXZ				6000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.503	mg	supplier	die	Silicon (Si)	7440-21-3		4.364	mg	969132	22367
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	2665	62
				supplier	metallization	Copper (Cu)	7440-50-8		0.040	mg	8883	205
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.005	mg	1110	26
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	1332	31
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	2443	56
				supplier	Passivation	Silicon Oxide	7631-86-9		0.065	mg	14435	333
Die Attach Epoxy_ABLEBOND 3230_H	M-011 Other inorganic materials	0.525	mg	Supplier	Metals	Silver	7440-22-4		0.473	mg	901000	2425
				Supplier	Plastics/polymers	Highly cross-linked polymer	Proprietary		0.052	mg	99000	266
Mold Compound_EME-G631SHQ_Sur	M-011 Other inorganic materials	120.501	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		2.533	mg	21000	12985
				Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		2.533	mg	21000	12985
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		6.756	mg	56000	34627
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		94.014	mg	780450	481865
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		13.912	mg	115320	71306
				Supplier	Non-metals	Carbon Black	1333-86-4		0.752	mg	6230	3852
Wire_AG SI TYPE_MKE	Bonding Wire	0.420	mg	Supplier	Metals	Silver	7440-22-4		0.404	mg	960000	2069
				Supplier	Metals	Others	Proprietary		0.017	mg	40000	86
Plating anode_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	5527
Leadframe_C9+Ag_HDS	Copper & its alloys	68.077	mg	Supplier	Metals	Iron	7439-89-6		1.489	mg	21865	7629
				Supplier	Non-metals	Phosphorus	7723-14-0		0.050	mg	730	255
				Supplier	Metals	Zinc	7440-66-6		0.077	mg	1125	393
				Supplier	Metals	Copper	7440-50-8		62.170	mg	913235	318651
				Supplier	Metals	Silver	7440-22-4		4.289	mg	63000	21982
				JIG-R	Metals	Lead	7439-92-1		0.003	mg	45	16